

ABSTRACT

A wiring board member for forming a multilayer wiring board includes an insulation layer (11) having a hole (11a) and a metal layer (12) as a conductive layer joined to the insulation layer. The metal layer (12) includes a via portion (12b) occupying the hold of the insulation layer, a bump portion (12a) integrally connected to the via portion, and a wiring part (12c). The bump portion is disposed on one surface of the insulation layer, and has a substantially truncated quadrangular pyramid shape with a bottom surface thereof being integrally connected to the via portion. The wiring part is disposed on the other surface of the insulation layer, and has a certain pattern.